**Product data sheet** 

# 1. General description

Ultrafast power diode in a TO247-2L plastic package.

## 2. Features and benefits

- · Fast switching and soft reverse recovery characteristics
- Low forward voltage drop
- · Low leakage current
- Low reverse recovery current
- Reduces switching losses in associated MOSFET or IGBT
- High operating temperature capability (T<sub>j (max)</sub> = 175°C)

# 3. Applications

- UPS
- EV Charger
- Welding Machine
- Air Conditioner

## 4. Quick reference data

### Table 1. Quick reference data

Symbol	Parameter	Conditions	Values			Unit
Absolute	maximum rating					
$V_{RRM}$	repetitive peak reverse voltage		600		V	
$I_{F(AV)}$	average forward current	$\delta$ = 0.5; $T_{mb} \le$ 132 °C; square-wave pulse; Fig. 1; Fig. 2; Fig. 3	60		А	
I <sub>FRM</sub>	repetitive peak forward current	$\delta$ = 0.5; t <sub>p</sub> = 25 μs; T <sub>mb</sub> ≤ 132 °C; square-wave pulse	120		А	
I <sub>FSM</sub>	non-repetitive peak forward current	$t_p$ = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 4				А
		$t_p$ = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse				Α
Symbol	Parameter	Conditions			Unit	
Static ch	aracteristics					
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 60 A; T <sub>j</sub> = 25 °C; <u>Fig. 6</u>	-	1.35	1.7	V
		I <sub>F</sub> = 60 A; T <sub>j</sub> = 150 °C; <u>Fig. 6</u>	-	1.1	1.4	V
Dynamic	characteristics		ı			
t <sub>rr</sub>	reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 100 \text{ A/}\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$	-	40	-	ns

# 5. Pinning information

## **Table 2. Pinning information**

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	А	anode		K —
mb	mb	mounting base; connected to cathode	K A TO247-2L	001aaa020

# 6. Ordering information

## **Table 3. Ordering information**

Type number	Package Name	Orderable part number		Small packing quantity	Package version	Package issue date
BYV60W-600PT2	TO247-2L	BYV60W-600PT2Q	Tube	30	TO247L-2L	28-Aug-2018

# 7. Marking

## Table 4. Marking codes

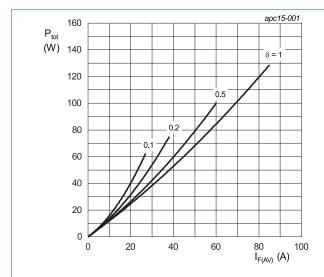
Type number	Marking codes
BYV60W-600PT2	BYV60W 600PT2

# 8. Limiting values

### **Table 5. Limiting values**

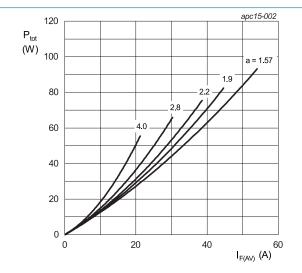
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
$V_{RRM}$	repetitive peak reverse voltage		600	V
$V_{RWM}$	crest working reverse voltage		600	V
$V_R$	reverse voltage	DC	600	V
I <sub>F(AV)</sub>	average forward current	$δ = 0.5$ ; $T_{mb} \le 132$ °C; square-wave pulse; Fig. 1; Fig. 2; Fig. 3	60	А
I <sub>FRM</sub>	repetitive peak forward current	$\delta$ = 0.5; t <sub>p</sub> = 25 μs; T <sub>mb</sub> ≤ 132 °C; square-wave pulse	120	А
I <sub>FSM</sub>	non-repetitive peak forward current	$t_p$ = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 4	600	А
		$t_p$ = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse	660	А
T <sub>stg</sub>	storage temperature		-55 to 175	°C
T <sub>j</sub>	junction temperature		175	°C



 $I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$  $V_o = 1.147 \text{ V; } R_s = 0.0043 \Omega$ 

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values



a = form factor =  $I_{F(RMS)}/I_{F(AV)}$ V<sub>o</sub> = 1.147 V; R<sub>s</sub> = 0.0043  $\Omega$ 

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

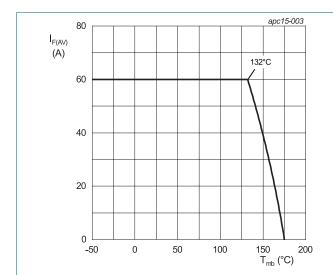


Fig. 3. Average forward current as a function of mounting base temperature; maximum values

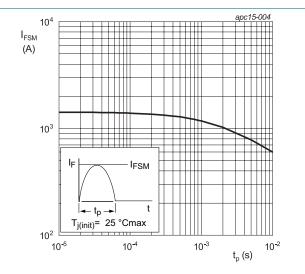


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

## 9. Thermal characteristics

**Table 6. Thermal characteristics** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base	Fig. 5	-	-	0.43	K/W
$R_{\text{th(j-a)}}$	thermal resistance from junction to ambient free air	in free air	-	40	-	K/W

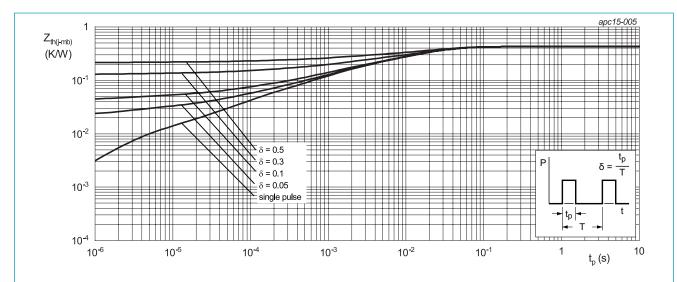
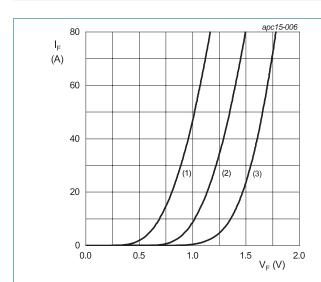


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration; maximum values

# 10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	aracteristics					
$V_{F}$	forward voltage	I <sub>F</sub> = 60 A; T <sub>j</sub> = 25 °C; <u>Fig. 6</u>	-	1.35	1.7	V
		I <sub>F</sub> = 60 A; T <sub>j</sub> = 125 °C; <u>Fig. 6</u>	-	1.2	1.5	V
		I <sub>F</sub> = 60 A; T <sub>j</sub> = 150 °C; <u>Fig. 6</u>	-	1.1	1.4	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 600 V; T <sub>j</sub> = 25 °C	-	-	10	μA
		V <sub>R</sub> = 600 V; T <sub>j</sub> = 125 °C	-	-	500	μA
Dynamic	characteristics				'	'
t <sub>rr</sub>	reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 100 \text{ A}/\mu\text{s};$ $T_j = 25 ^{\circ}\text{C}; Fig. 7$	-	40	-	ns
		$I_F = 50 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$	-	79	-	ns
		$I_F = 50 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s};$ $T_j = 125 \text{ °C}; Fig. 7$	-	145	-	ns
I <sub>RM</sub>	peak reverse recovery current	$I_F = 50 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$	-	8.3	-	А
		$I_F = 50 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s};$ $T_j = 125 \text{ °C}; Fig. 7$	-	18.5	-	А
$Q_r$	recovered charge	$I_F = 50 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$	-	325	-	nC
		$I_F = 50 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 200 \text{ A}/\mu\text{s};$ $T_i = 125 \text{ °C}; Fig. 7$	-	1345	-	nC



(1)  $T_j$  = 150 °C; typical values (2)  $T_j$  = 150 °C; maximum values (3)  $T_j$  = 25 °C; maximum values  $V_o$  = 1.147 V;  $R_s$  = 0.0043  $\Omega$ 

Fig. 6. Forward current as a function of forward voltage

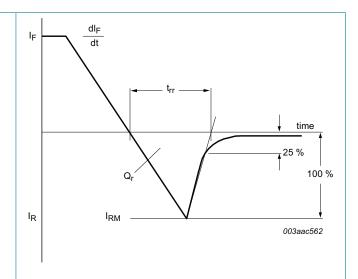
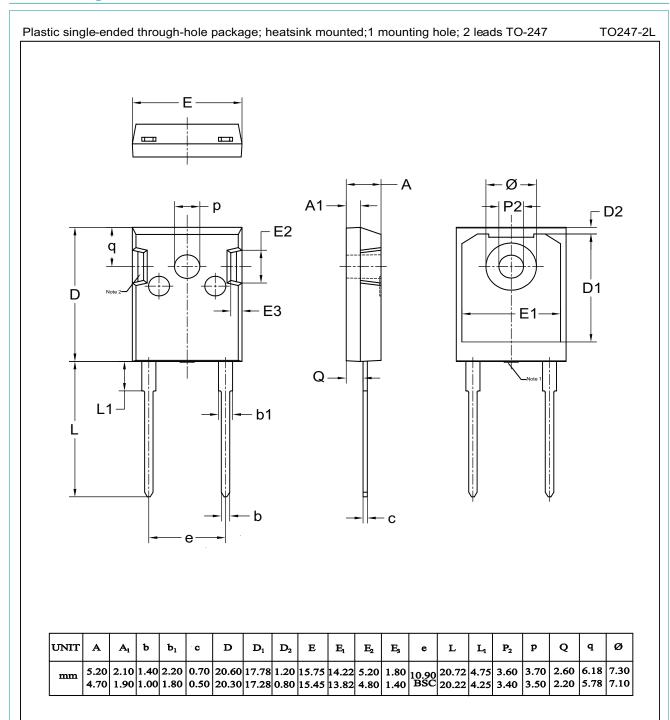


Fig. 7. Reverse recovery definitions; ramp recovery

# 11. Package outline



#### Note:

- Mold resin protrusion max 0.127mm.
- Metal exposed with Sn plating.

## 12. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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